

INTERNATIONAL STANDARD

NORME INTERNATIONALE

Semiconductor devices – Hot carrier test on MOS transistors

Dispositifs à semiconducteurs – Essai de porteur chaud sur les transistors MOS



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IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland
Email: inmail@iec.ch
Web: www.iec.ch

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Tél.: +41 22 919 02 11

Fax: +41 22 919 03 00



IEC 62416

Edition 1.0 2010-04

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INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

PRICE CODE
CODE PRIX

K

ICS 31.080

ISBN 978-2-88910-695-0

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
HOT CARRIER TEST ON MOS TRANSISTORS**

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The text of this standard is based on the following documents:

FDIS	Report on voting
47/2041/FDIS	47/2048/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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SEMICONDUCTOR DEVICES – HOT CARRIER TEST ON MOS TRANSISTORS

1 Scope

This standard describes the wafer level hot carrier test on NMOS and PMOS transistors. The test is intended to determine whether the single transistors in a certain (C)MOS process meet the required hot carrier lifetime.

2 Abbreviations and letter symbols

In this document the following abbreviations and letter symbols apply:

MOS	Metal Oxide Semiconductor
NMOS	n-channel MOS transistor
PMOS	p-channel MOS transistor
(C)MOS	Complementary MOS
L [μm]	length of polysilicon gate of MOS transistor
W [μm]	width of polysilicon gate of MOS transistor
L_{nominal} [μm]	minimum L allowed by the design rules of the process
W_{nominal} [μm]	minimum W allowed by the design rules of the process
V_{gs} [V]	gate-source voltage of MOS transistor
V_{ds} [V]	drain-source voltage of MOS transistor
V_{bs} [V]	backgate-source voltage of MOS transistor
I_{ds} [μA]:	drain-source current of MOS transistor
I_{b} [μA]	substrate current of MOS transistor
I_{g} [nA]	gate current of MOS transistor
$V_{\text{gs, stress}}$ [V]	V_{gs} biasing condition during hot carrier stress
$V_{\text{ds, stress}}$ [V]	V_{ds} biasing condition during hot carrier stress
$V_{\text{ds, use_max}}$ [V]	maximum V_{ds} allowed by the design rules of the process as stated in the design manual
$V_{\text{ds, breakdown}}$ [V]	V_{ds} at which avalanche or punch-through currents become dominant; defined as V_{ds} at which $I_{\text{ds}} = 1,5 \times (I_{\text{ds}} \text{ at } V_{\text{ds, use_max}})$ while $V_{\text{gs}} = V_{\text{ds, use_max}}$
V_{t} [V]	threshold voltage of MOS transistor defined as V_{gs} voltage at which $I_{\text{ds}} = 0,01 \times W / L$ [μA]. Other (commonly agreed) definitions of V_{t} are also allowed as long as this is clearly reported.
g_{m} [$\mu\text{A/V}$]	transconductance of MOS transistor
$g_{\text{m, max}}$ [$\mu\text{A/V}$]	maximum transconductance of MOS transistor
$I_{\text{ds, sat}}$ [μA]	saturated drain-source current at $V_{\text{gs}} = V_{\text{ds}} = V_{\text{ds, use_max}}$; $I_{\text{ds, sat_forward}}$ measured with source and drain having same polarity as during stress, $I_{\text{ds, sat_reverse}}$ measured with source and drain polarity interchanged with respect to stress.
L (MOST)	length of the square MOS transistor ($L = W$)
$g_{\text{m, max}}$ (MOST)	$g_{\text{m, max}}$ of the square MOS transistor ($L = W$)